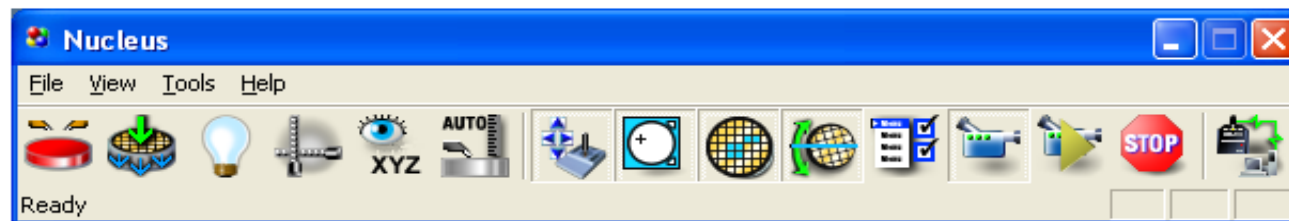
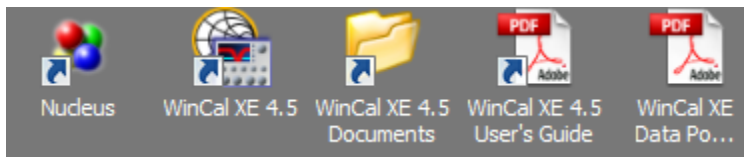


Purpose of Demonstration: Using VueTrack/eVue for Automatically- Corrected Small-Pad Probing over Temperature

Documentation is located at: Start...All Programs....Cascade Microtech...Nucleus; let's take a quick look at that.

Double-click on the Nucleus icon to start the program.



Open the needed Nucleus Tools and Components

Motion Control

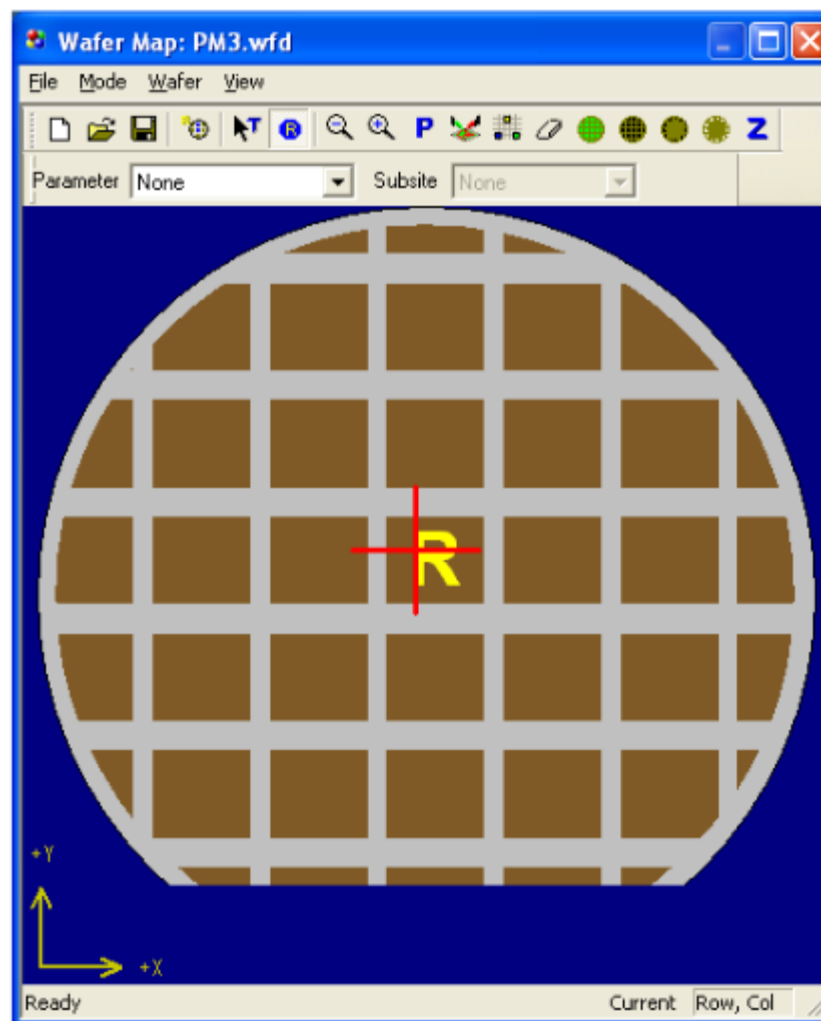
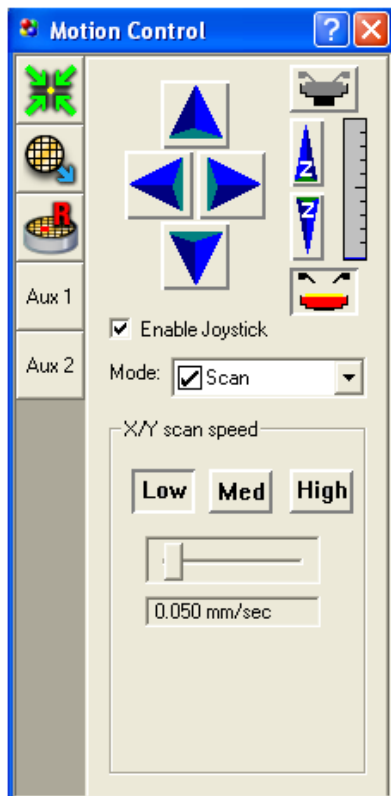
Wafer Map

Align Tool

Measurement Tool

Video

Automation XYZ



**Align** [?] [X]

2 Point Align | Soft Align | Hard Align | Auto Align

Alignment Type

☒ Wafer Alignment

☐ ISS/Module Alignment

Stage Motion Options

☐ Horizontal Stage Moves

☒ Vertical Stage Moves

Auto-Align Target Image

Alignment Options

☐ Extra Fine Alignment

☒ Run Auto XY Die Size

☐ Coarse Pre-Align

☒ Use eVue Focus Adjust

☐ Use Die Size

X 30000

Y 20000

Start

Redo Last Align

Vision Options

Close

**Measure Distance** [?] [X]

Instructions:  
Move to a location on a die. After moving, click 'Start Pos'.  
Enter estimated row and column sizes. The sizes will be  
used for computing the number of rows and columns  
traversed between points.

Distance X [ ] Microns

Distance Y [ ] Microns

Num Columns [ ]

Num Rows [ ]

Column Size (estimate) 30000 Microns

Row Size (estimate) 20000 Microns

Die XY Size Mode

☒ Auto

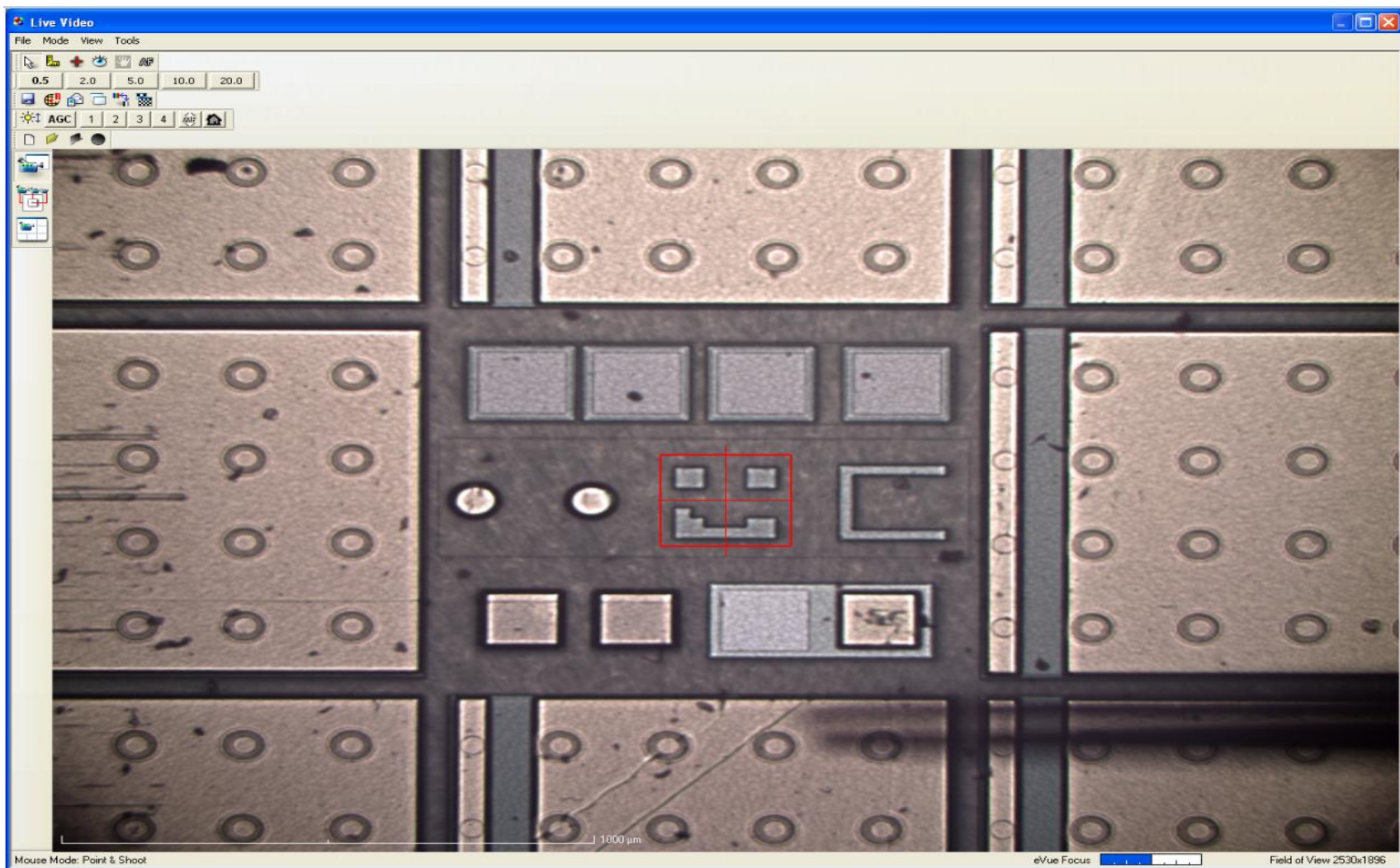
☐ Manual

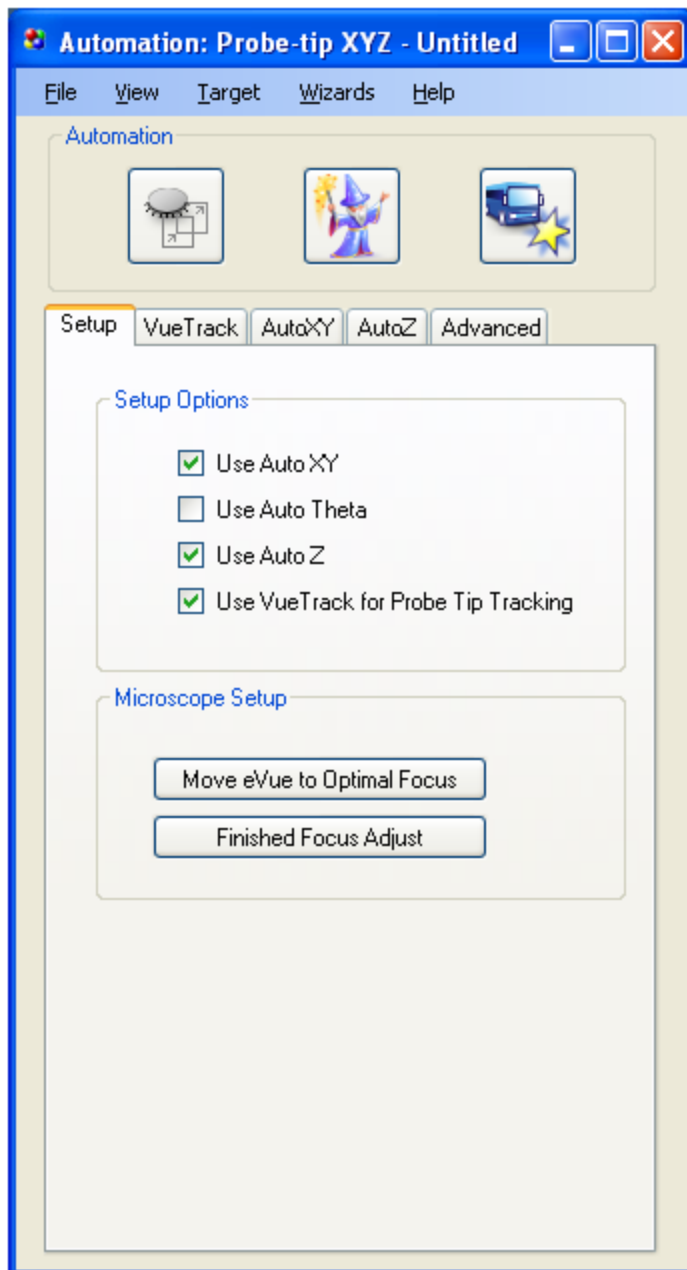
Start

Abort

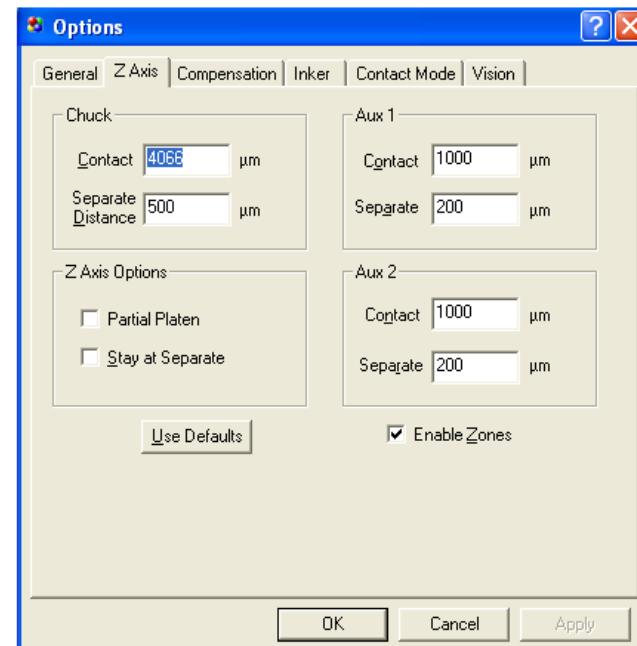
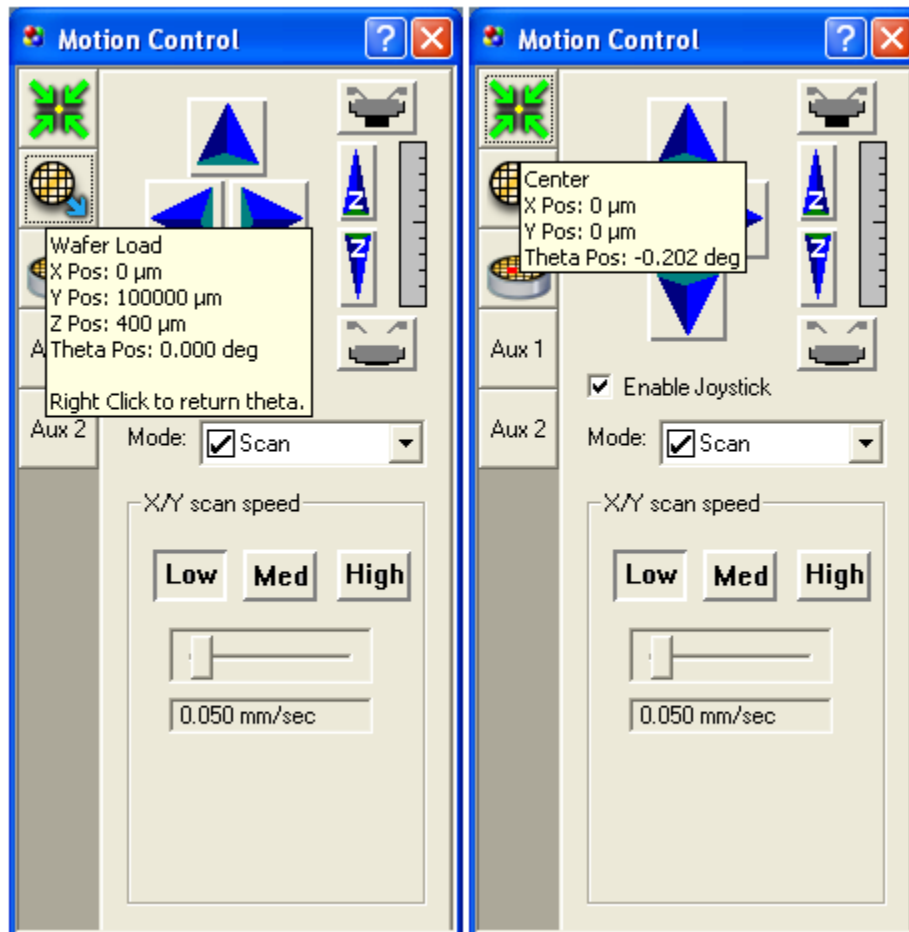
Copy To Wafer Map

Set Distance Comp.



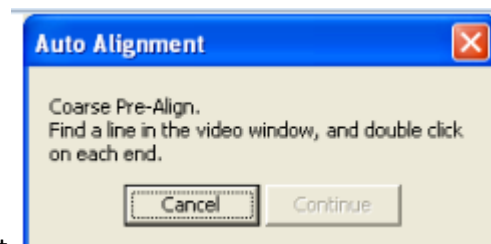
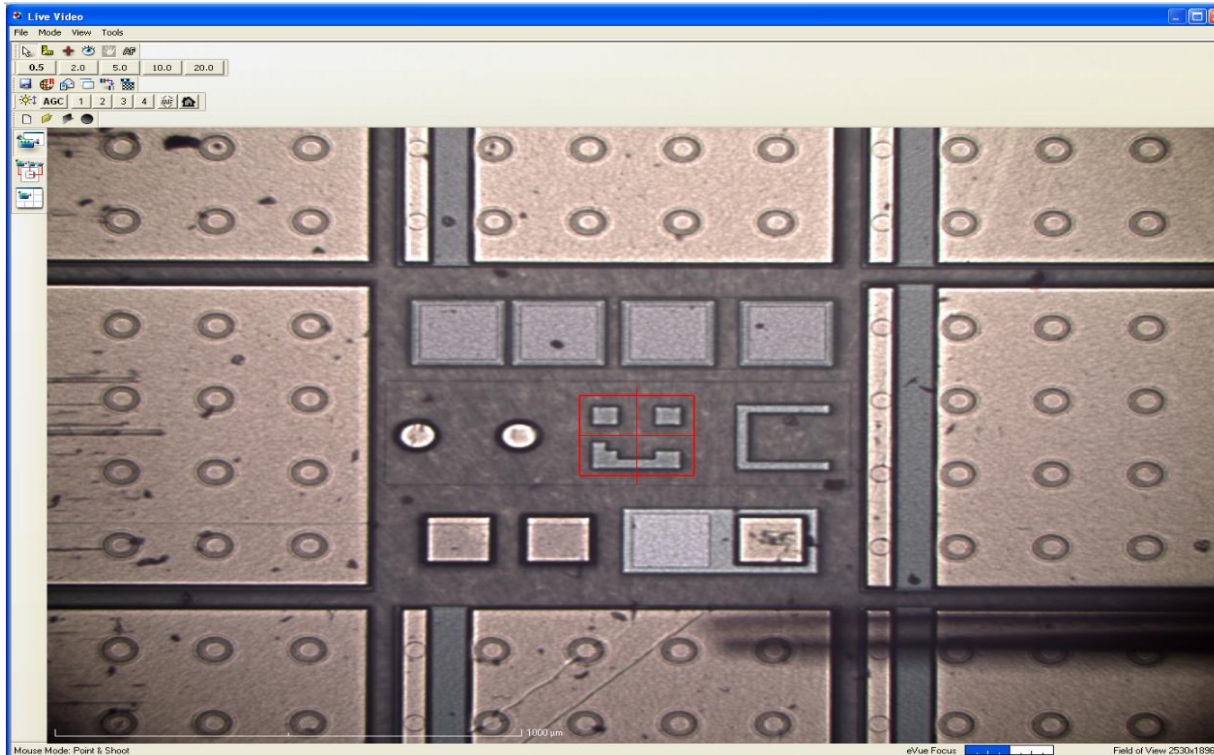


Use Motion Control to load and center the wafer (as well as adjust the chuck height, if necessary)



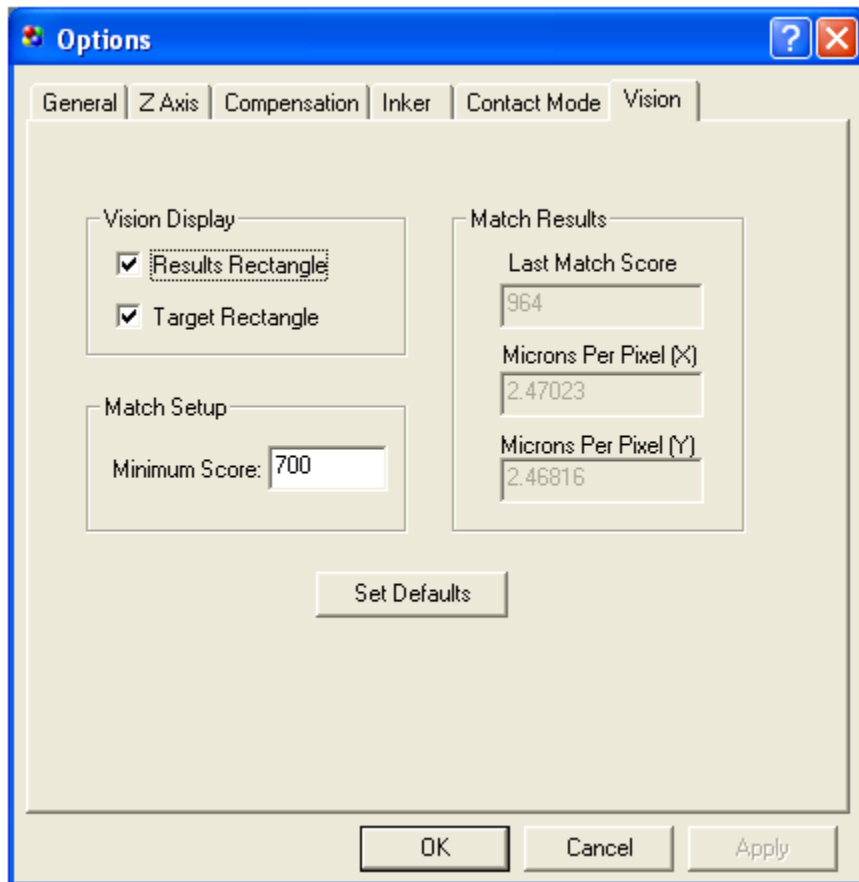
Now that we've seen the wafer, we know its size and orientation on the chuck and can set up the wafer map per the additional hand-out, "Wafer Map Details."

Once the wafer map is ready, we'll align the wafer and determine the die size. We focus on a feature that is seen only once per die.



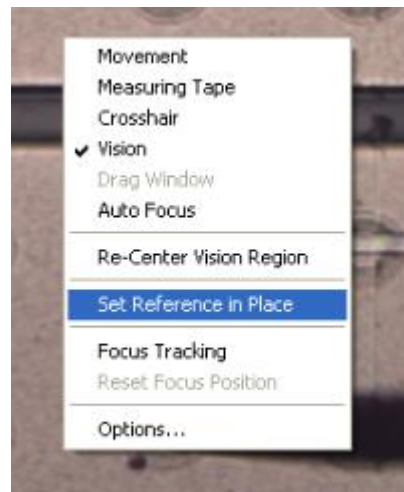
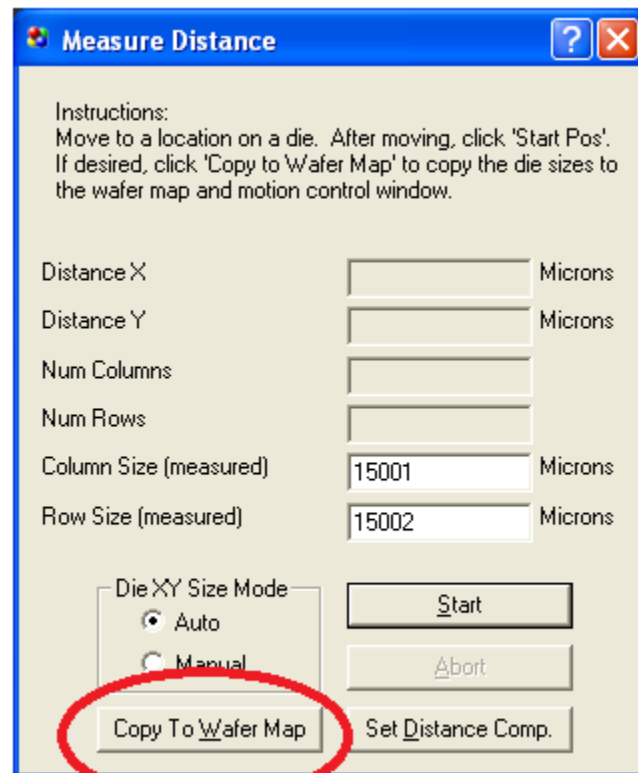
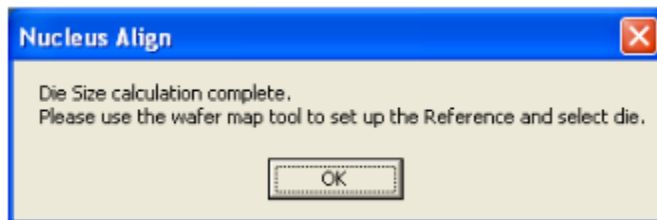
The coarse pre-align is done first

We note that we may need to adjust the Match Setup score in Options as necessary to recognize the chosen target in subsequent die.

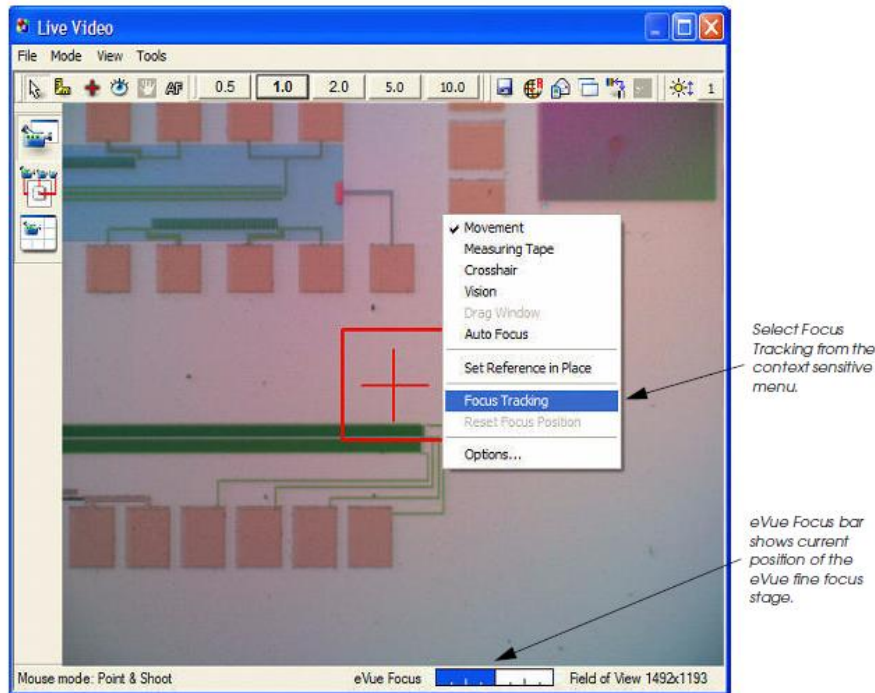




The die size is next determined (note that “Copy to Wafer Map” is no longer grayed-out in the Distance Measurement tool window) and we copy it to the wafer map. We also set reference in place though we’ll change it later.



Make sure focus tracking is off.....



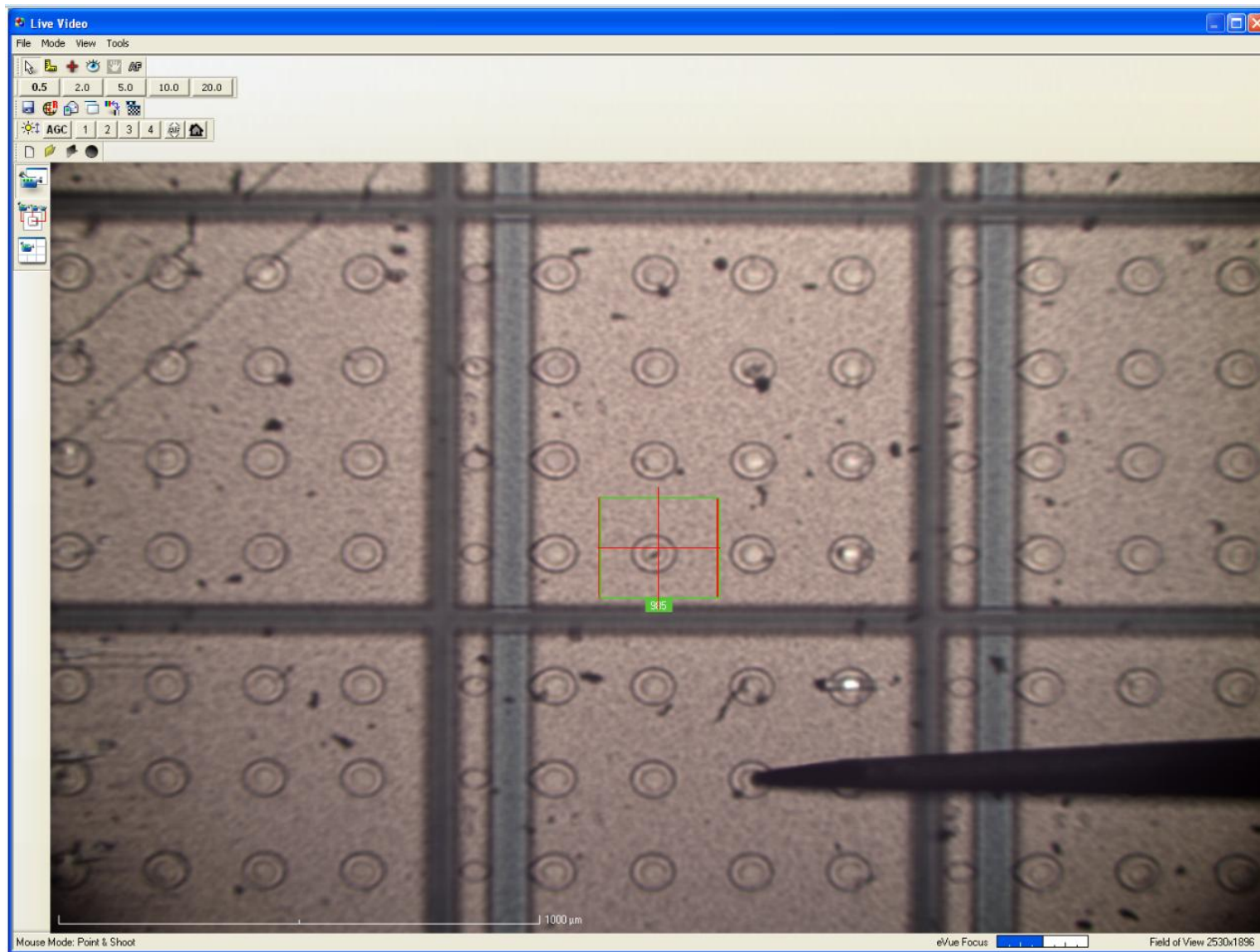
To enable Focus Tracking, click OK.



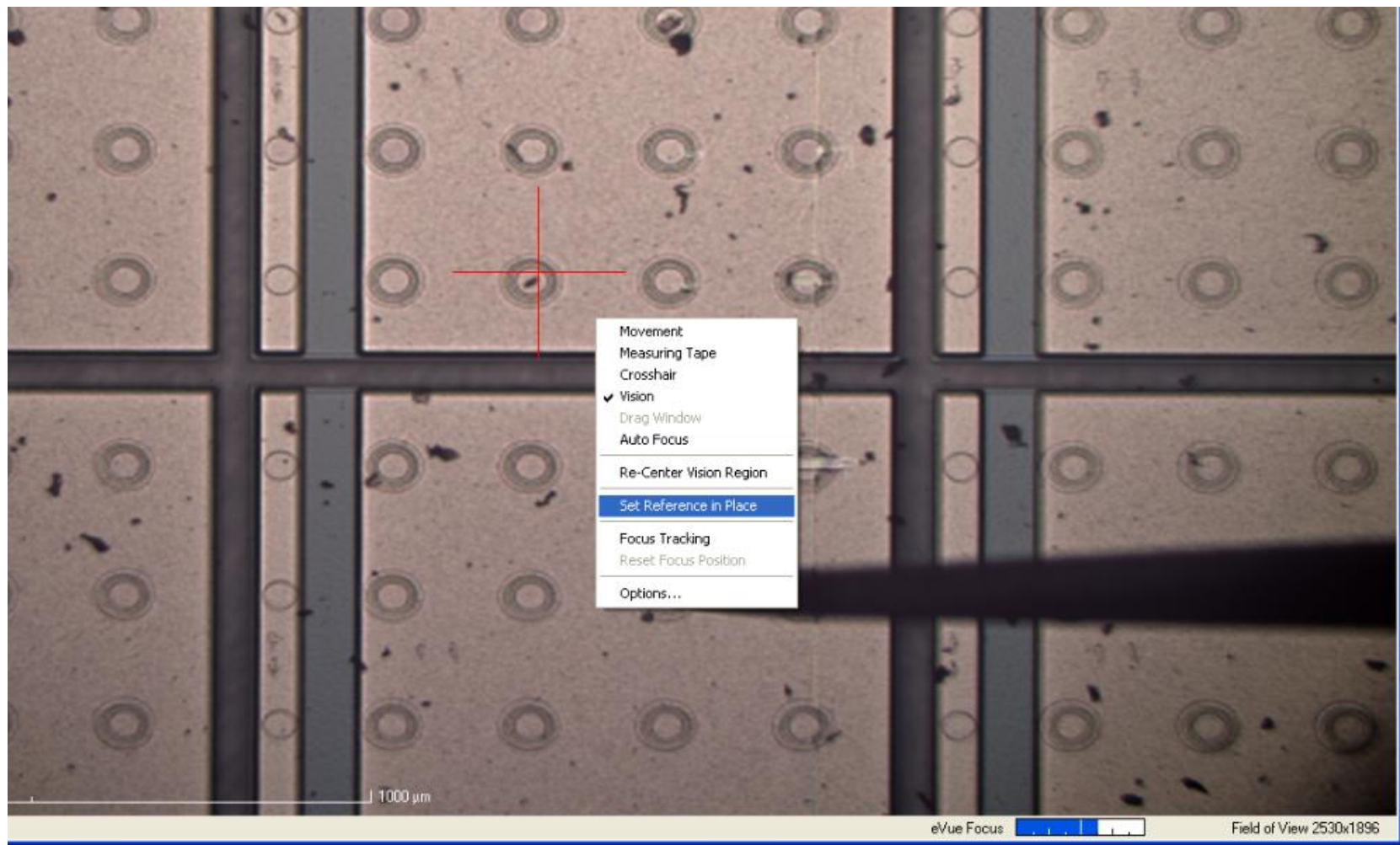
Focus Tracking synchronizes the current eVue fine focus position to the Stage Z position. From this point on, any movement of stage Z causes the eVue fine focus stage to track to the new position. This is useful for keeping the wafer in focus at all times, whether you are at separate or contact.

When Focus Tracking is enabled, the Reset Focus Position option is available. The Reset Focus Position option resynchronizes the current stage Z and eVue fine focus stage positions.

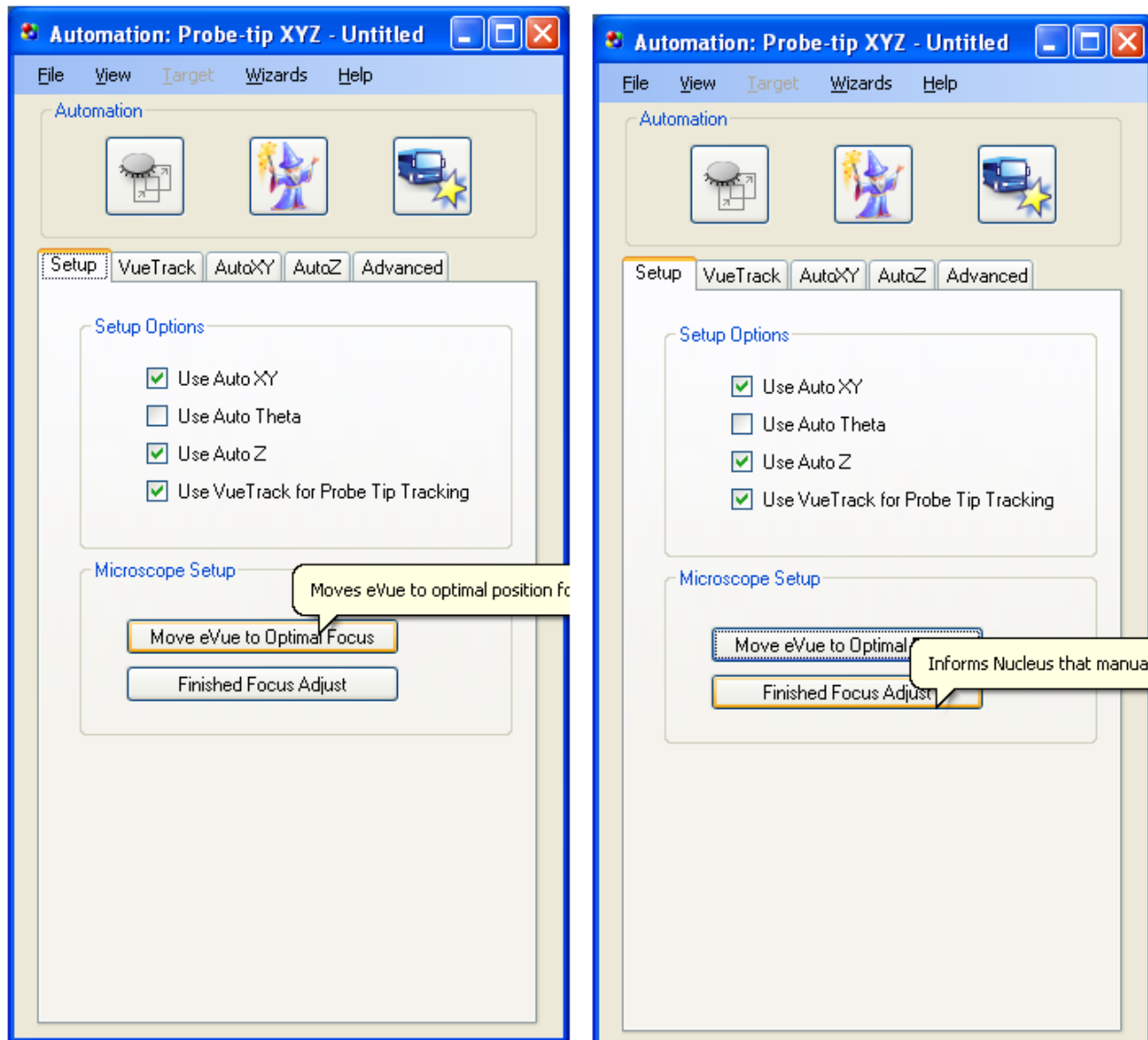
Probe to pad.....



After probe to pad is accomplished, set reference in place.



We next set up the Automation XYZ. Additional set-up details are provided in the additional handout: "Quick Start Guide for AUTO XYZ."



Automation: Probe-tip XYZ - Untitled

File View Target Wizards Help

Automation

Setup VueTrack AutoXY AutoZ Advanced

Probe Card Setup

Pad Size

X	50	μm
Y	50	μm

Probe Tip

Size	10	μm
Max Δ Z	50	μm

☐ Continue on error

Modify...

Probe tips

Probe Tip Targets: 0 Layout

Train

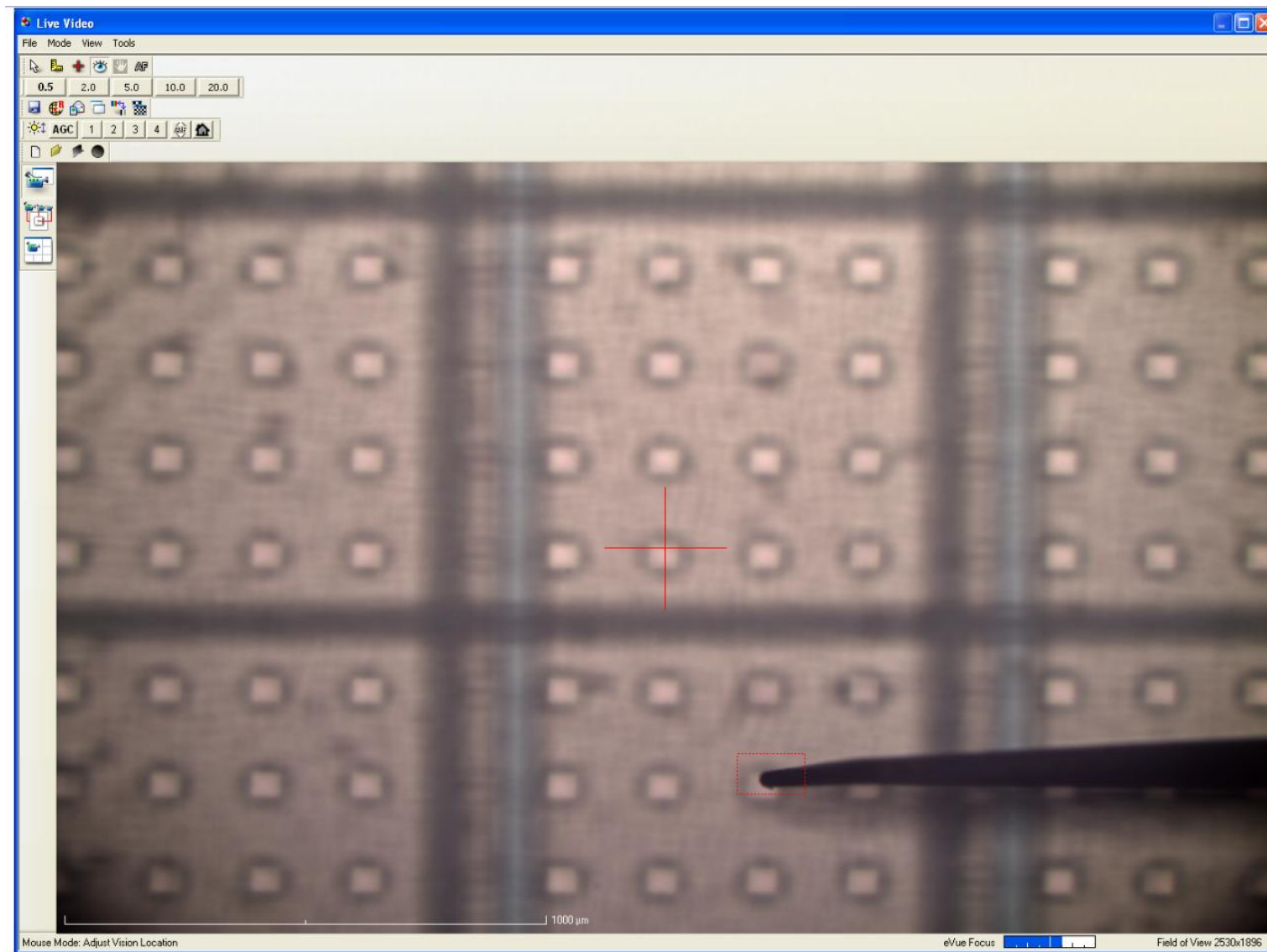
Verify Layout

Finished

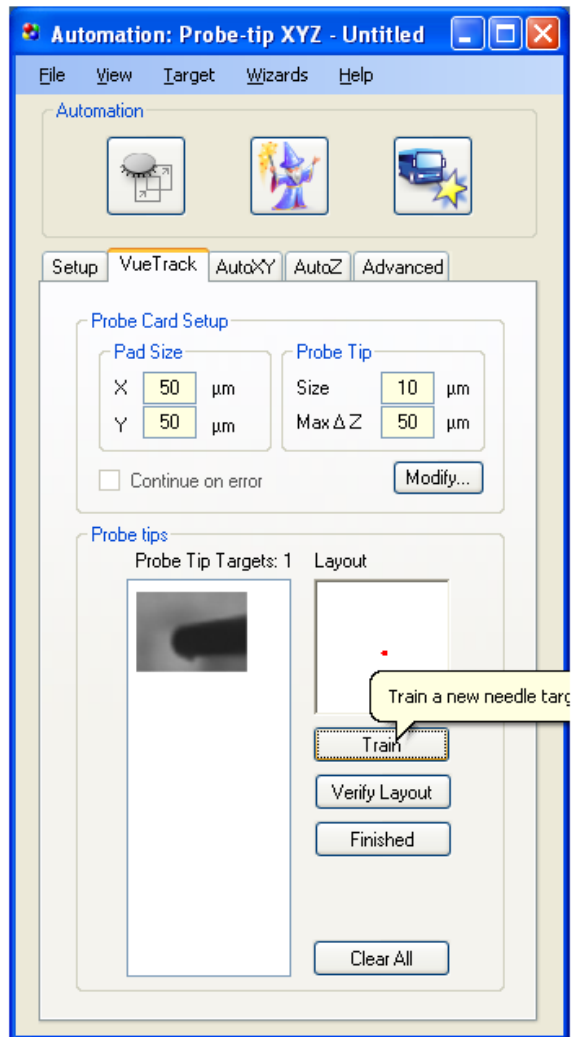
Clear All



We click on the “EyeBall” to select the training area for establishing the probe tip reference.

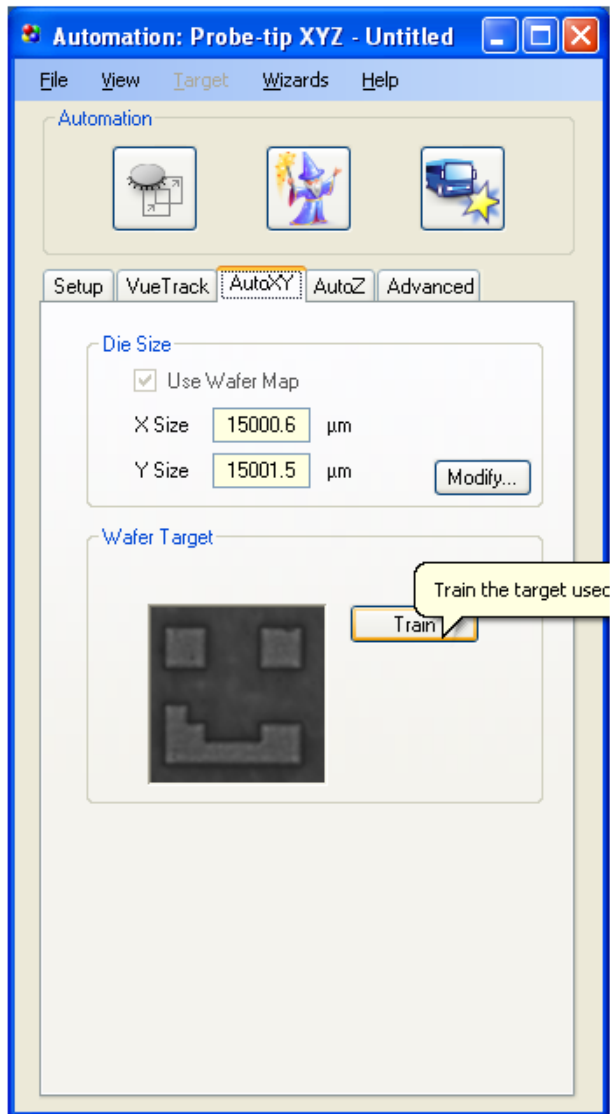


We can train on up to ten probe tip targets.

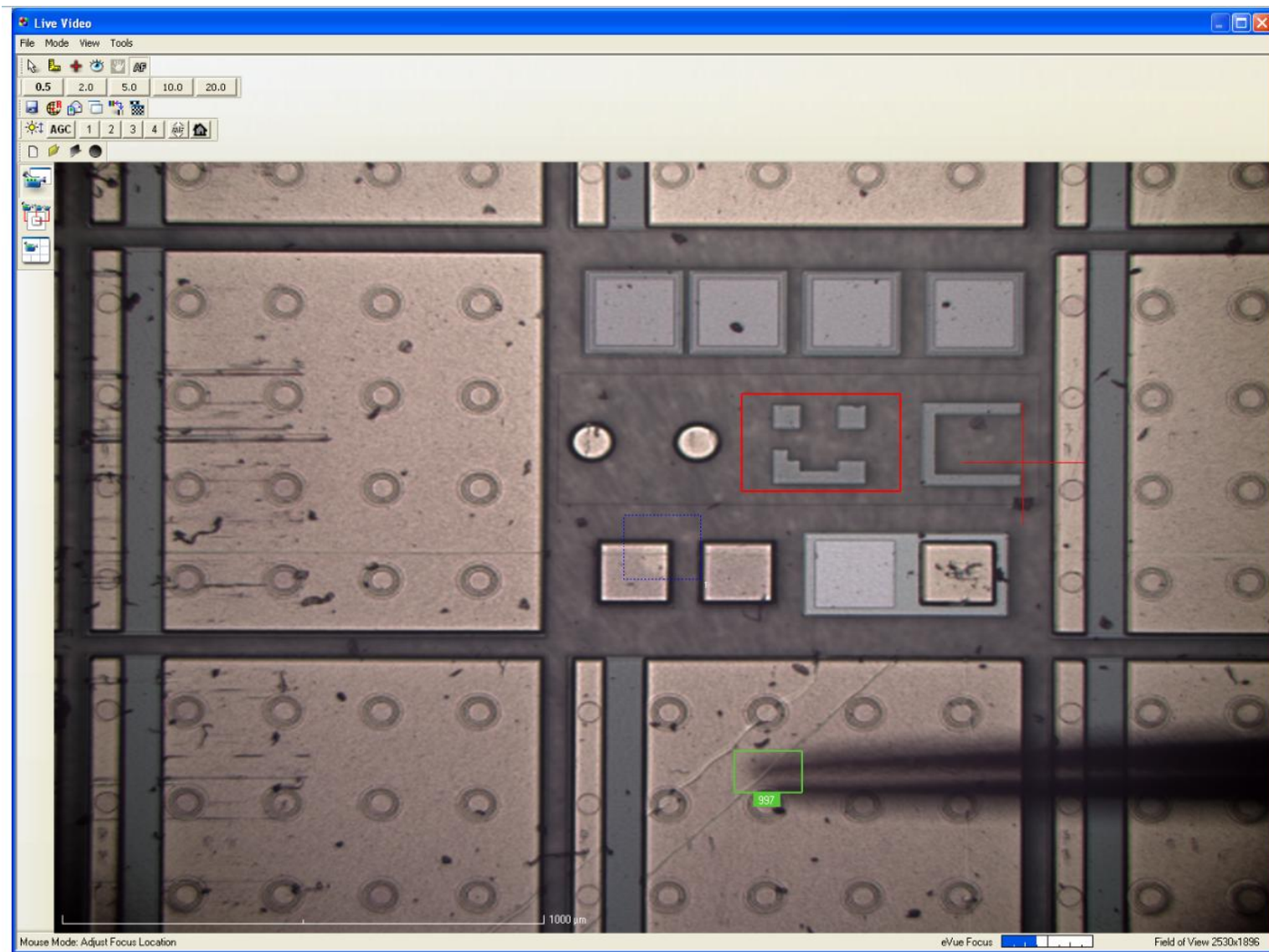




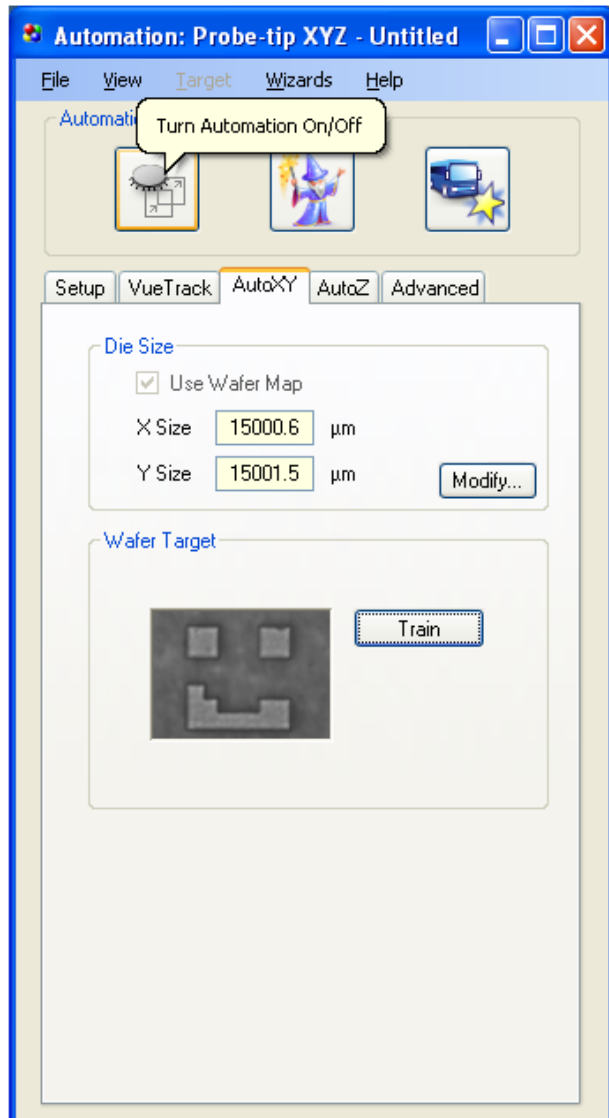
We next train on a wafer target to establish the wafer plane. This should be outside the probe card area.



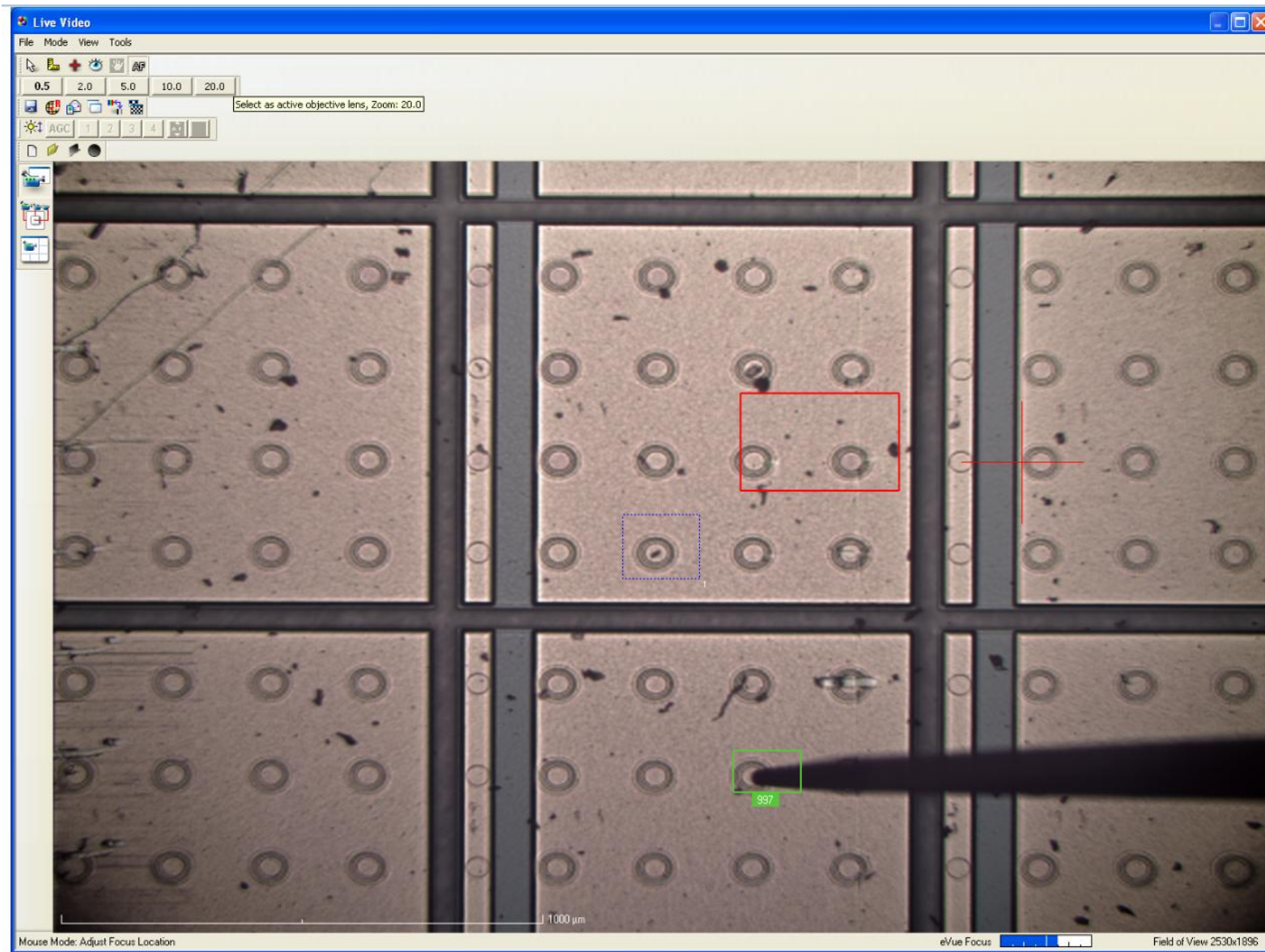
We use the “Eyeball” to designate a target; note that the blue AutoFocus block is located on another area. Let’s discuss that.....



When finished training the wafer target we turn on Automation.

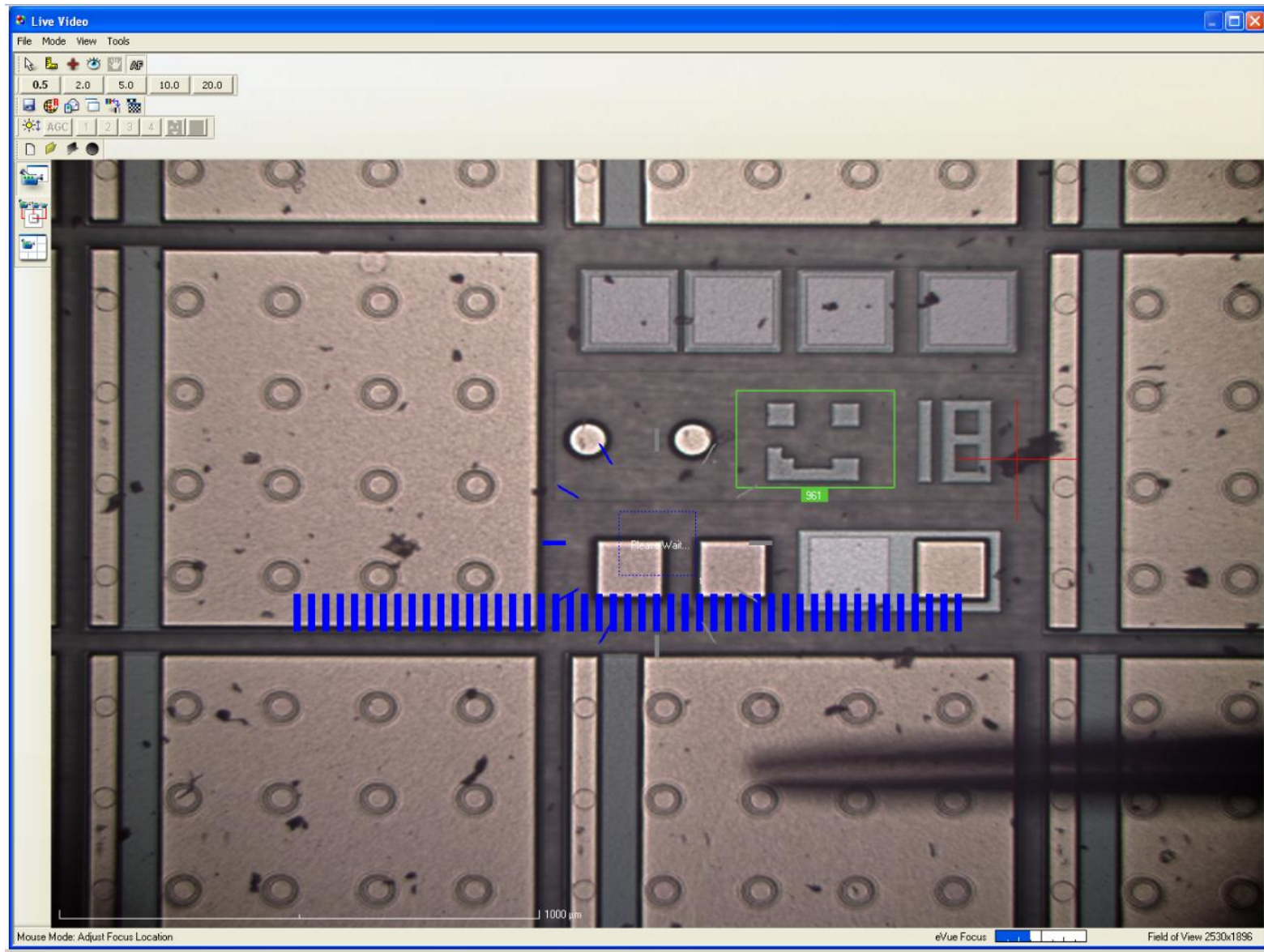


When we turn on Automation the chuck goes to contact at the trained position with probe to pad.





We click on the wafer map to step to another location. The probe goes first to the trained wafer site, acquires the target



And then brings the wafer and probe in contact.....

